

SOT1134-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 60 terminals; UTLP based

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN60U
Package type industry code	HXQFN60U
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	22-1-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.46	-	0.48	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	60	-	



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2. Package outline

HXQFN60U: plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based; body 4 x 6 x 0.5 mm

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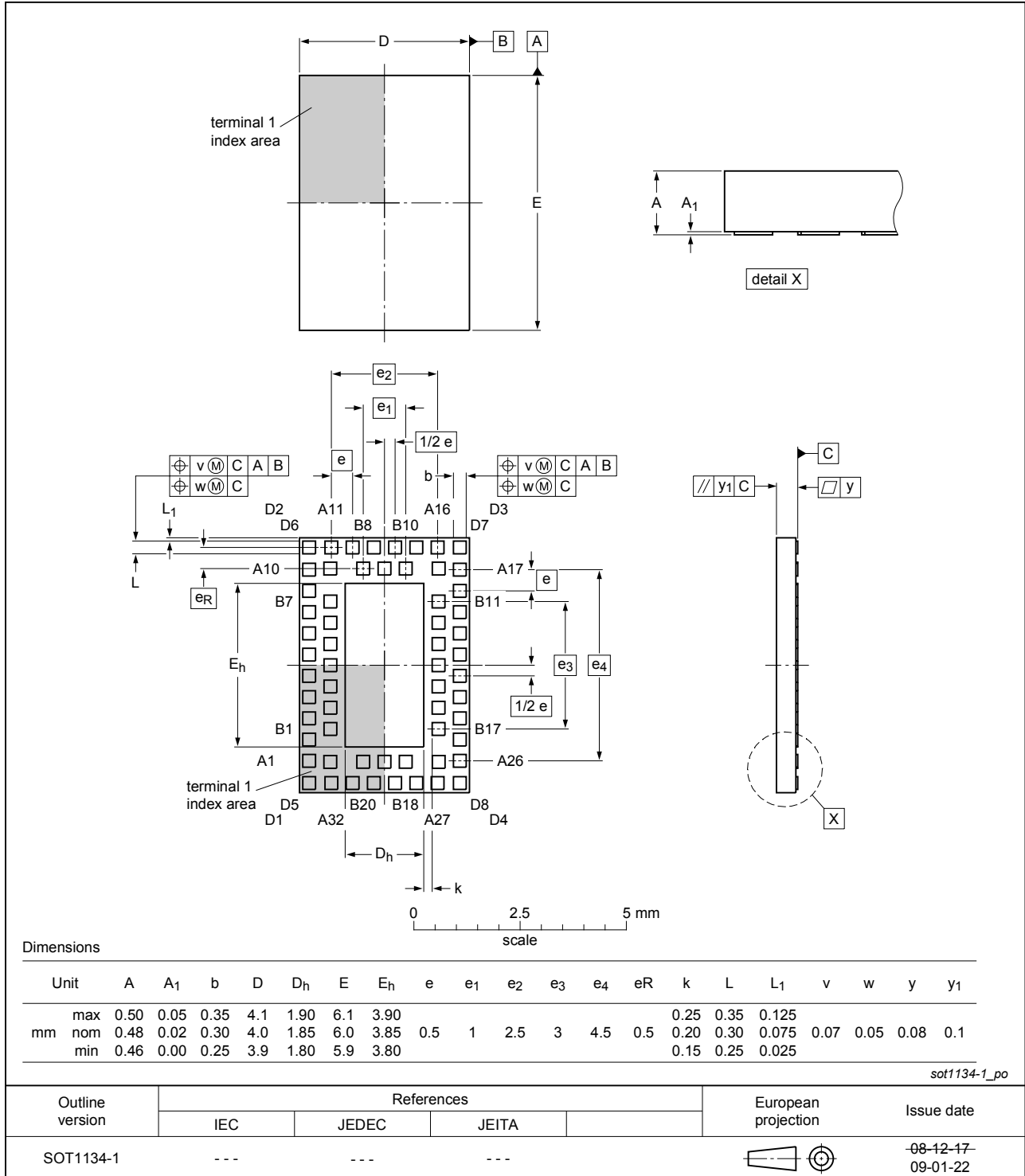


Fig. 1. Package outline HXQFN60U (SOT1134-1)

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3. Soldering

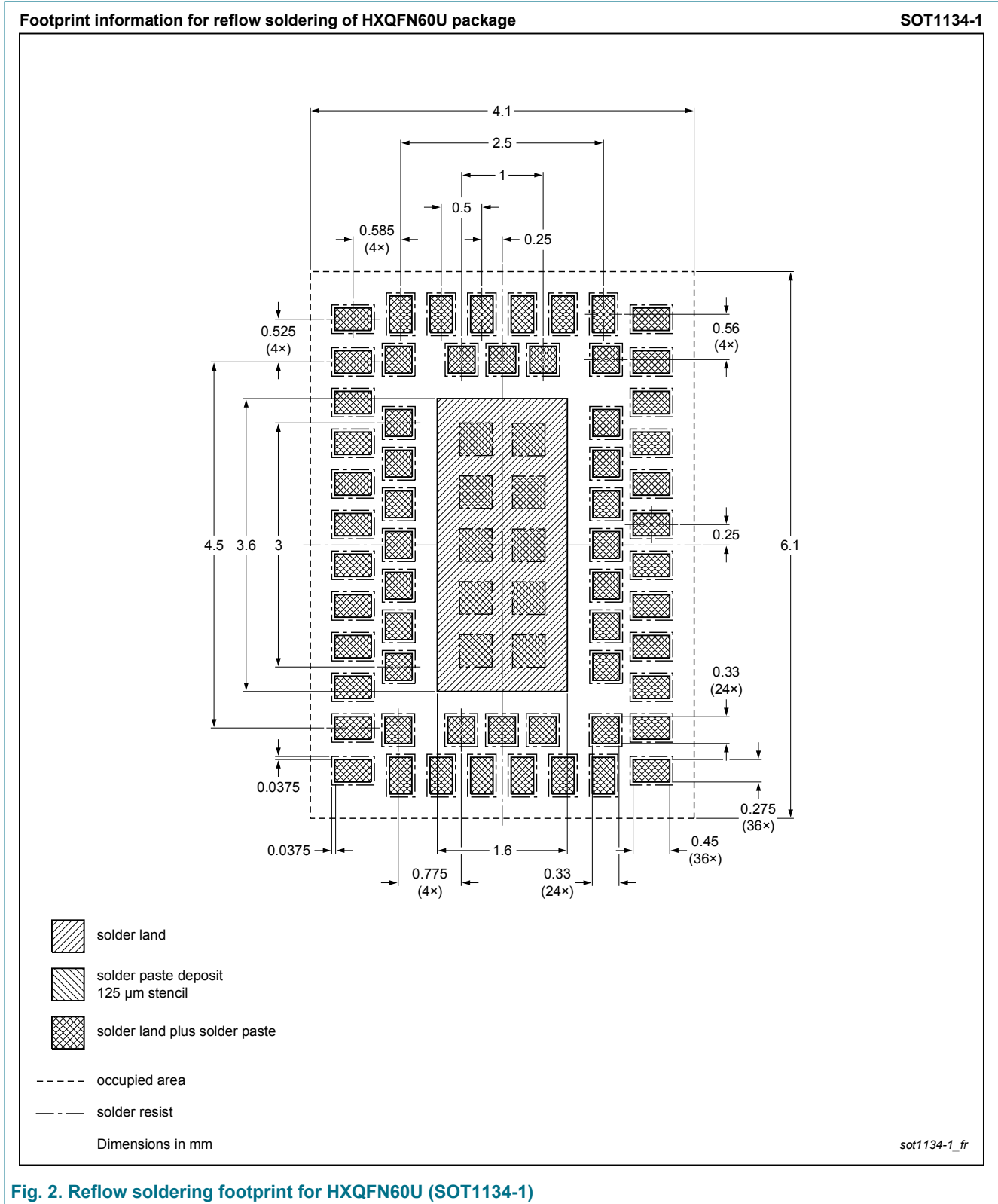


Fig. 2. Reflow soldering footprint for HXQFN60U (SOT1134-1)

4. Legal information

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